



Application Data Sheet

Application Information

Application Number:: 10681583
Filing Date:: 10/08/2003
Application Type:: Regular
Subject Matter:: Utility
Title:: Semiconductor multi-package module having
inverted second package stacked over ~~die-down~~
die-up flip-chip ball grid array (BGA) package
Attorney Docket Number:: CPAC 1029-5 D3
Total Drawing Sheets:: 20
Small Entity?:: No

Applicant Information

Applicant Authority Type: Inventor
Primary Citizenship Country: US
Status: Full Capacity
Given Name: Marcos
Family Name: Karnezos
City of Residence: Palo Alto
State or Province of Residence: CA
Country of Residence: US
Street of mailing address: 535 Lytton Avenue
City of mailing address: Palo Alto
State or Province of mailing address: CA
Country of mailing address: US
Postal or Zip Code of mailing address: 94301



Correspondence Information

Correspondence Customer Number:: 22470

Representative Information

Representative Customer Number::	22470	
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Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Non-Provisional of	60/417,277	October 8, 2002
This Application	Non-Provisional of	60/460,541	April 4, 2003
This Application	Continuation-in-Part of	10/618,933	July 14, 2003
10/618,933	Non-Provisional of	60/460,541	April 4, 2003

Assignee Information

Assignee name:: ChipPAC, Inc.
Street of mailing address:: 47400 Kato Road
City of mailing address:: Fremont
State or Province of mailing address:: CA
Country of mailing address:: US
Postal or Zip Code of mailing address:: 94538